

Burn-in Testing Techniques for Electronic Devices

Application Note



Contents

Introduction	1
Burn-in Test during Manufacturing Process	1
Advantages of Agilent's USB DAQ in Burn-in Test	2
Conclusion	3
References	3
Related Agilent Literature	3

Introduction

Electronic devices are routinely tested multiple times during the manufacturing process, which includes the wafer level, module level and module burn-in tests.

Systems and materials begin to wear out upon usage, and various mechanisms can lead to failure. Therefore, failures are defined within specific bounds under specific tolerance limits. Early failures may come from poor design or improper manufacturing.

Accelerated life tests that subject units to higher-than-usual levels of stress, like voltage, temperature, humidity, pressure and loading tests, are used to speed up the deterioration of materials or electronic components. This enables analysts to collect failure information more quickly. About 40% of microelectronic failures are reported to be due to temperature. In other words, this means temperature is the most critical factor for component failure. Burn-in is a screening technique performed by applying high voltage and temperature at a product life cycle's early stage to remove latent defects. It is used for highly integrated circuit system.

Burn-in Test during Manufacturing Process

Burn-in tests require the consideration of several factors when choosing a solution. These include device power, method of temperature measurement and power requirements. All of these affect the thermal resistance of the device, which ultimately affects the capability to stress devices at high temperature.

It is important to note that there are various types of temperature sensors and data acquisition (DAQ) to choose from. Agilent itself has more than 15 USB DAQ devices to choose from and each one has its own advantages for a specific application.

When selecting the optimum DAQ system for burn-in test, there are various aspects to consider.



Typical aspects include the below:

- Number of channels
- Sampling rate
- Cost-effective high volume solution
- High accuracy of device under test (DUT)
- Test the DUT control and measurement
- Minimal floor space or compact system
- High level of temperature control

It is essential to use a stable and highly accurate DAQ device in each of the above features. Since the DAQ system is designed for general usage, they are affordable, easy to use, do not consume too much space and does not damage the DUT.

In order to obtain accurate measurements, Agilent USB high performance multifunction DAQ device provides the total solution and meets the increasingly demanding reliability testing challenges.

Figure 1 illustrates an example of a burn-in test system in an environmental chamber. The system uses a temperature sensor and Agilent high performance USB DAQ device to obtain temperature measurement.

Advantages of Agilent's USB DAQ in Burn-in Test

Agilent USB DAQ device offers 64-CH single-ended or 32-CH differential analog inputs, with up to 3 MSa/s sampling rate and A/D resolution of 12 bits and 16 bits. With the 64-CH single ended or 32-CH differential analog inputs, the DUT operating voltages are closely verified and monitored. As a result, a large number of DUTs can be monitored efficiently and continuously.

Monitoring of current drawn of each DUT can provide an excellent insight to the proper operation of the DUT. Voltage outputs produced by inductive current sensors or shunt resistors can be monitored by the Agilent USB high performance multifunction DAQ device.

Voltage levels from either type of current sensor are compared to user-defined high and low limits of the DAQ system. The failure is displayed and logged if the limit is exceeded.

Thermal control during test and burn-in plays a key role in reducing cost and increasing production yield. Device temperature is measured by attaching a small thermocouple directly on the device or by using sensors integrated into the device. Accurate temperature measurement plays a crucial role for burn-in system in order to obtain an accurate data. Agilent high performance multifunction USB DAQ device provides one of the best solutions with its 64-CH single ended or 32-CH differential analog inputs.

With its sampling rate of up to 3 MSa/s, the Agilent high performance multifunction USB DAQ device provides a broader range of input signals to be sampled at one time. Users can obtain higher accuracy of measured data by performing the burn-in test with a larger sample size of input signals.

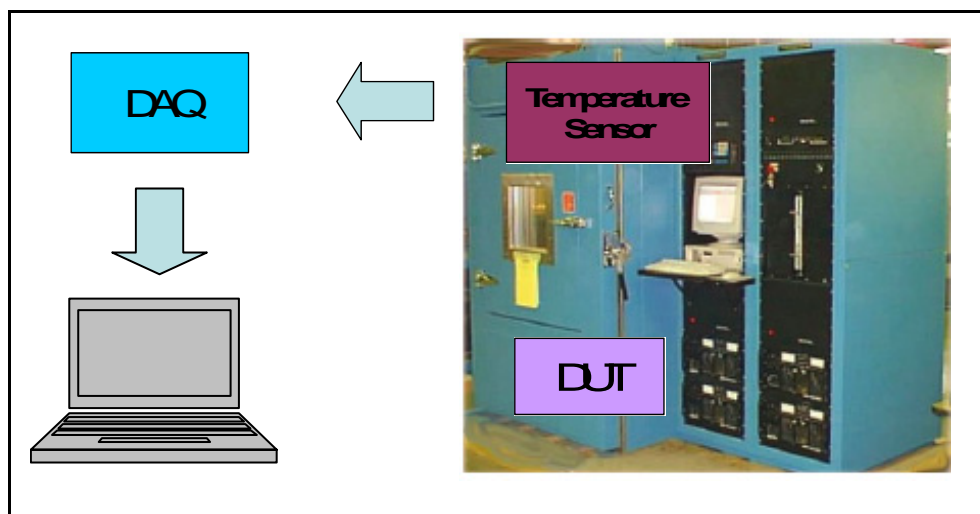


Figure 1 Burn-In test in an environmental chamber

When an input signal is taken, the sampled analog signal must be converted from a voltage value to a binary number so that the value can be read. The A/D converter uses a finite number of evenly spaced values to represent the analog signal. The number of different values is determined by the number of bits used for the conversion. Most modern converters use 12 bits or 16 bits.

Today, USB is a widely used interface device. Its low cost and simplicity makes it a great choice when you need to create a quick test solution. This short time-to-measure feature of USB is particularly attractive in engineering labs and other environments where instruments are frequently moved, shared, and reconfigured. To facilitate these applications, the Agilent high performance multifunction DAQ devices offer USB connectivity.

With its intended use in consumer applications, USB is not only inexpensive and widely used (it is in every PC today) but also easy to use. Benefits of USB are as follows:

- increased productivity
- low cost
- production space saving for burn-in test system.

Conclusion

Most electronic components have an infant mortality period of about one year under ordinary operating conditions. The reliability problem in the infant mortality period becomes extremely important. The main purpose of performing burn-in is to guarantee customers high reliability of the products.

Agilent USB high performance multifunction DAQ device has top class features to meet the increasing demand reliability testing and guarantees high reliability of end products. In addition to this, Agilent also offers basic multifunction, simultaneous sampling, analog output and digital I/O DAQ devices. Agilent has more than 15 USB DAQ products that provide one of the best solutions to customers.

References

- David Gardell, *Temperature Control During Test and Burn-in*
- Way Kuo, Fellow, IEEE and Taeho Kim, *An Overview of Manufacturing Yield and Reliability Modeling for Semiconductor Products*
- Steven Petersen, Product Test Solutions, Thermotron Industries, *The Application of Burn-in to DC/DC Converter Production Testing*

Related Agilent Literature

- *System Developer Guide – Using USB in the Test and Measurement Environment* (Application Note 1465- 12)

Additional information is also available at www.agilent.com/find/U2300A or contact your nearest Agilent sales office or sales representative.

www.agilent.com
800 123-4567



Agilent Email Updates

www.agilent.com/find/emailupdates

Get the latest information on the products and applications you select.

Agilent T&M Software and Connectivity

Agilent's Test and Measurement software and connectivity products, solutions and developer network allows you to take time out of connecting your instruments to your computer with tools based on PC standards, so you can focus on your tasks, not on your connections.

Visit www.agilent.com/find/connectivity for more information.

By internet, phone, or fax, get assistance with all your test & measurement needs.

Online assistance:

www.agilent.com/find/assist

Phone or Fax

United States:

(tel) 800 829 4444

(fax) 800 829 4433

Canada:

(tel) 877 894 4414

(fax) 800 746 4866

China:

(tel) 800 810 0189

(fax) 800 820 2816

Europe:

(tel) (31 20) 547 2111

(fax) (31 20) 547 2390

Japan:

(tel) (81) 426 56 7832

(fax) (81) 426 56 7840

Korea:

(tel) (82 2) 2004 5004

(fax) (82 2) 2004 5115

Latin America:

(tel) (650) 752 5000

Taiwan:

(tel) 0800 047 866

(fax) 0800 286 331

Other Asia Pacific Countries:

(tel) (65) 6375 8100

(fax) (65) 6836 0252

Email: tm_ap@agilent.com

Product specifications and descriptions in this document subject to change without notice.

© Agilent Technologies, Inc. 2006
Printed in USA, November 7, 2006
5989-5560EN



Agilent Technologies